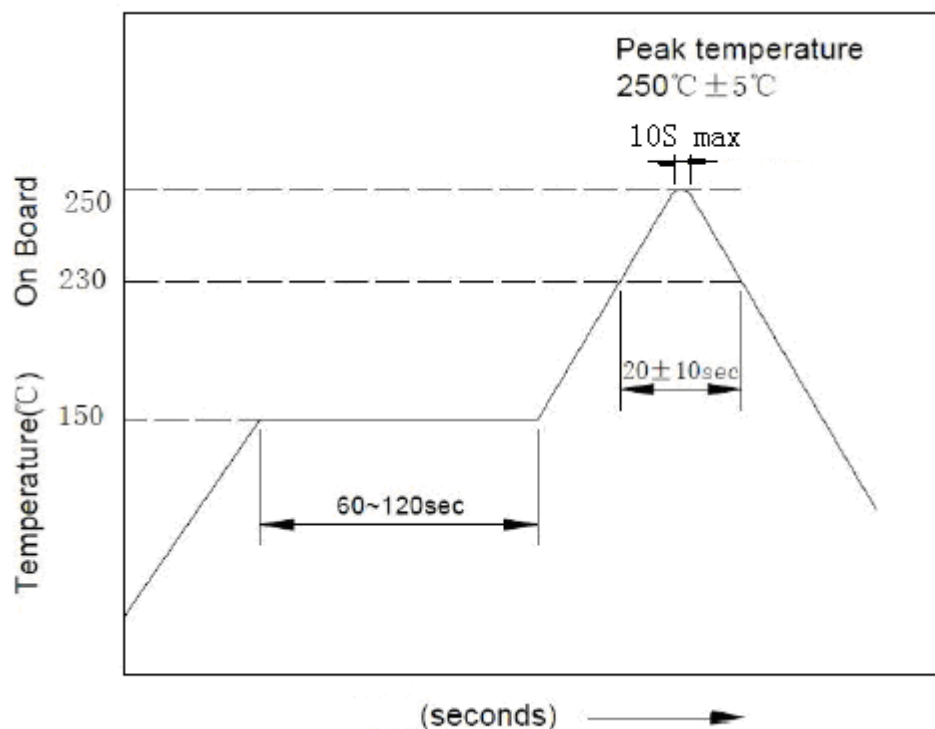
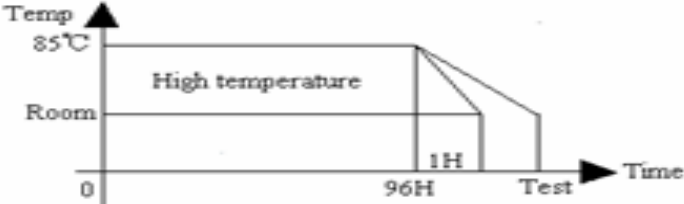
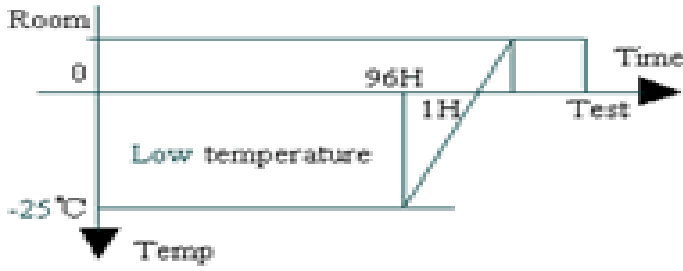
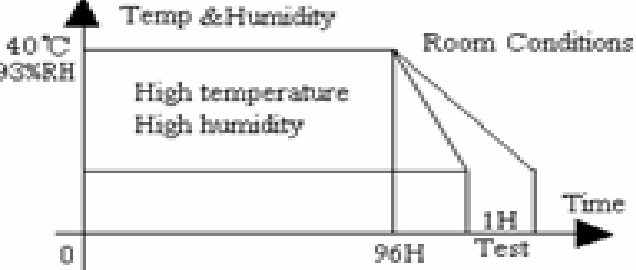
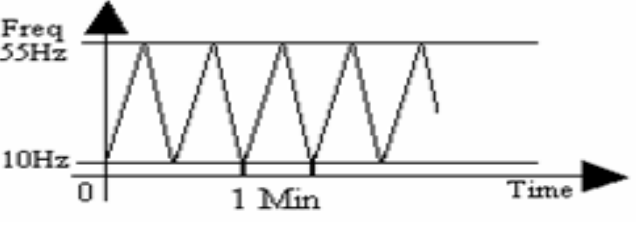
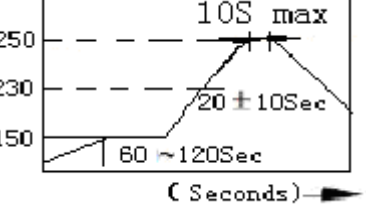


- Under 350 Degrees, Within 3 seconds, 2 Rounds -



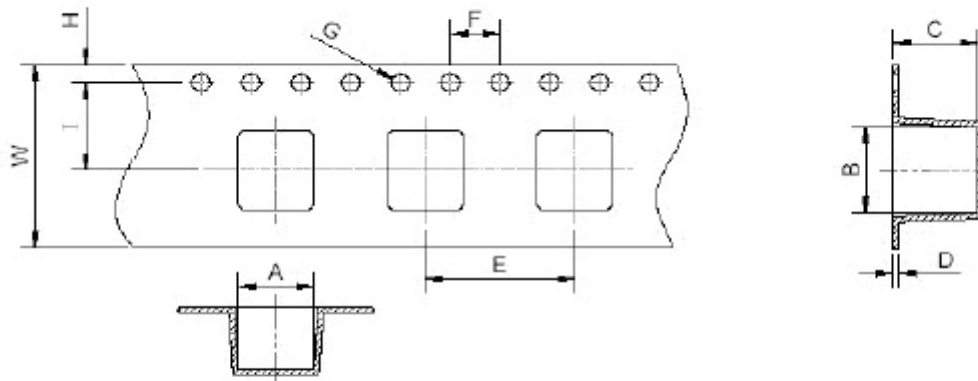
Stability and Test Conditions

Item	Requirement	Test Method
MIL-STD-202G Method 108A *High Temperature Storage Test	1. No obvious appearance defects 2.Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	Temp:85±2°C; Time:96±2 hours, set the samples in room temp for 1 hour, test within 2 hours 
IEC 68-2-1A 6.1 6.2 *Low Temperature Storage Test	1. No obvious appearance defects 2.Changes of inductance	Temp:-25±2°C; Time:96±2hours, set the samples in room temp for 1 hour, test within 2 hours.

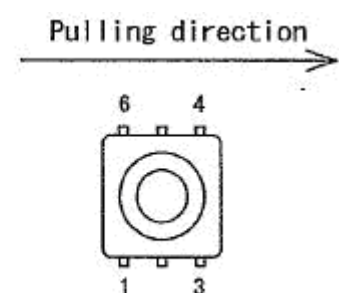
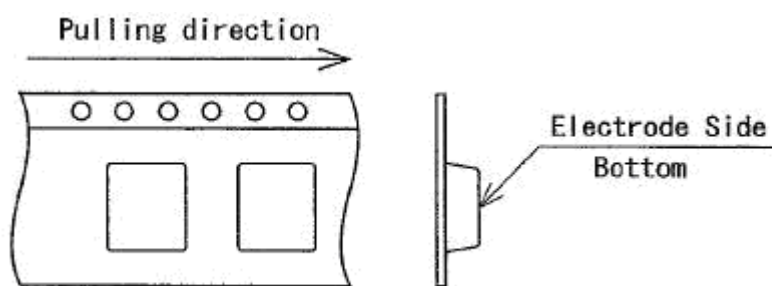
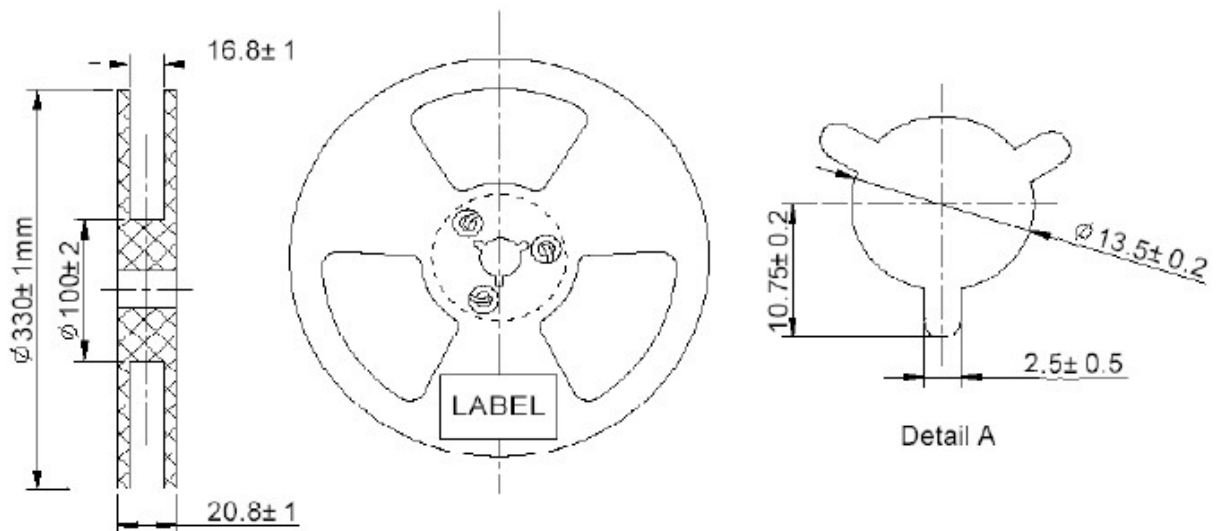
	under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	
MIL-STD-202G Method 103B *Humidity Test	1. No obvious appearance defects 2. Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	1. Dry the samples in $40\pm 5^{\circ}\text{C}$ temp condition for 24 hours 2. Test after drying 3. Expose: Temp $40\pm 2^{\circ}\text{C}$, Humidity $93\pm 3\%\text{RH}$, for 96 ± 2 hours 4. Test in the chamber after exposing 5. Set the samples in room temp for 1 hour, test within 2 hours. 
MIL-STD-202G Method 208H IPC-J-STD-002B * Solderability Test	95% solder coverage	1. Immerse the solder in the flux, then immerse the solder into $245\pm 5^{\circ}\text{C}$ lead-free solder furnace for 5 seconds 2. To solder: Sn(63)/Pb(37) 3. Flux: rosin
MIL-STD-202G Method 201A *Vibration Test	1. No obvious appearance defects 2.Changes of inductance under 10% 3.Changes of Quality Factor under 30% 4.Changes of DC resistance under 10%	Vibrate along the x, y and z axis with 10-55Hz Vibration rate and 0.75mm amplitude for individually 2 hours (Total 6 hours) 
* Solder heat resistance test	1. Smear soldering paste on circuit board, solder at 350 degrees for 2 times. The Pin won't come off and the bottom won't deform . 2. After soldering the reflow at 250 degrees for 3 seconds, the Pin won't come off and the bottom won't deform	(Reflow) 

Tape Dimensions

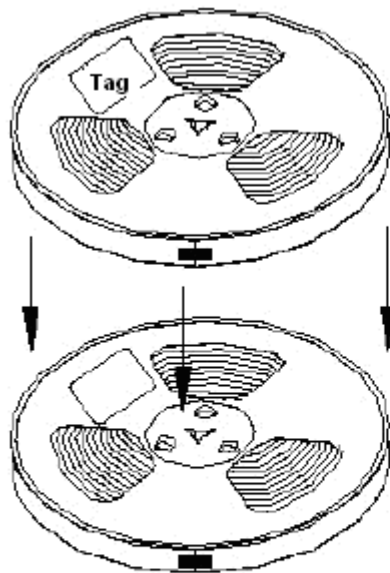
Tape Dimensions



	W=16 ^{±0.3} mm		Unit: mm						
ITEM	A	B	C	D	E	F	G	H	I
DIM	6.56	8.0 ^{±0.2}	6.51	0.5 ^{±0.05}	12 ^{±0.2}	4.0 ^{±0.1}	1.5 ^{±0.1}	1.75 ^{±0.1}	7.5 ^{±0.2}

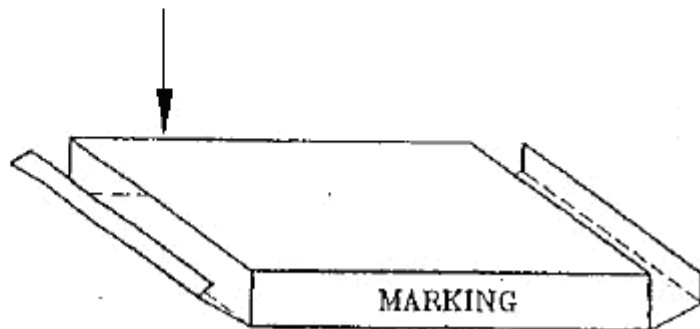


Package



Packaging Requirement:
900pcs / per tray

3 Trays / per Box
(2700pcs)



2 Boxes / per carton

